



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET



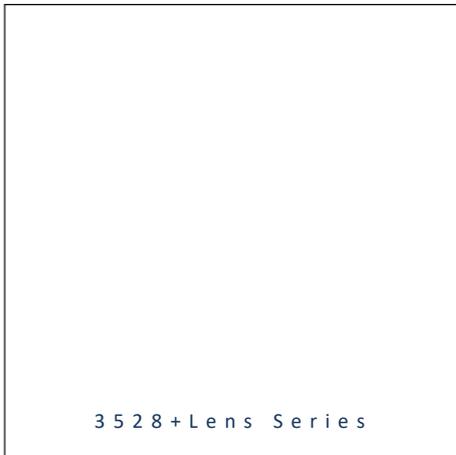
- ▶ PLCC2 Top View
- ▶ 3528+Lens Series
- ▶ Cyan (500nm)

NOB53S01 (13" reel)

NOB53S01SR (7" reel)



Release Date: 18 July 2024 Version: A1.2



3528+Lens Series

3528+Lens Series



FEATURES:

- **Package:** PLCC2 SMT Package with Lens
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 3.2V
- **Luminous Intensity (typ.):** 5900mcd@20mA
- **Colour:** Cyan
- **Dominant Wavelength (typ.):** 500nm
- **Viewing Angle:** 30°
- **Materials:**
 - Die: InGaN/GaN
 - Resin: Epoxy (Water Clear)
 - L/F Finish: Ag Plated
- **Operating Temperature:** -40~+80°C
- **Storage Temperature:** -40~+85°C
- **Grouping Parameters:**
 - Forward voltage
 - Luminous intensity
 - Dominant wavelength
- **Soldering Methods:** Reflow soldering
- **MSL Level:** acc. to JEDEC Level 3
- **Packing:** 12mm tape with max.2000pcs/reel, ø330mm (13") or max.600pcs/reel ø180mm (7")

APPLICATIONS:

- LED Display
- Indicator
- Traffic Display
- Decoration Lighting
- Railway Singal

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30	mA
Peak Forward Current Duty 1/8@1KHz	I _{FP}	125	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μA
Power Dissipation	P _D	111	mW
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T _{STG}	-40~+85	°C

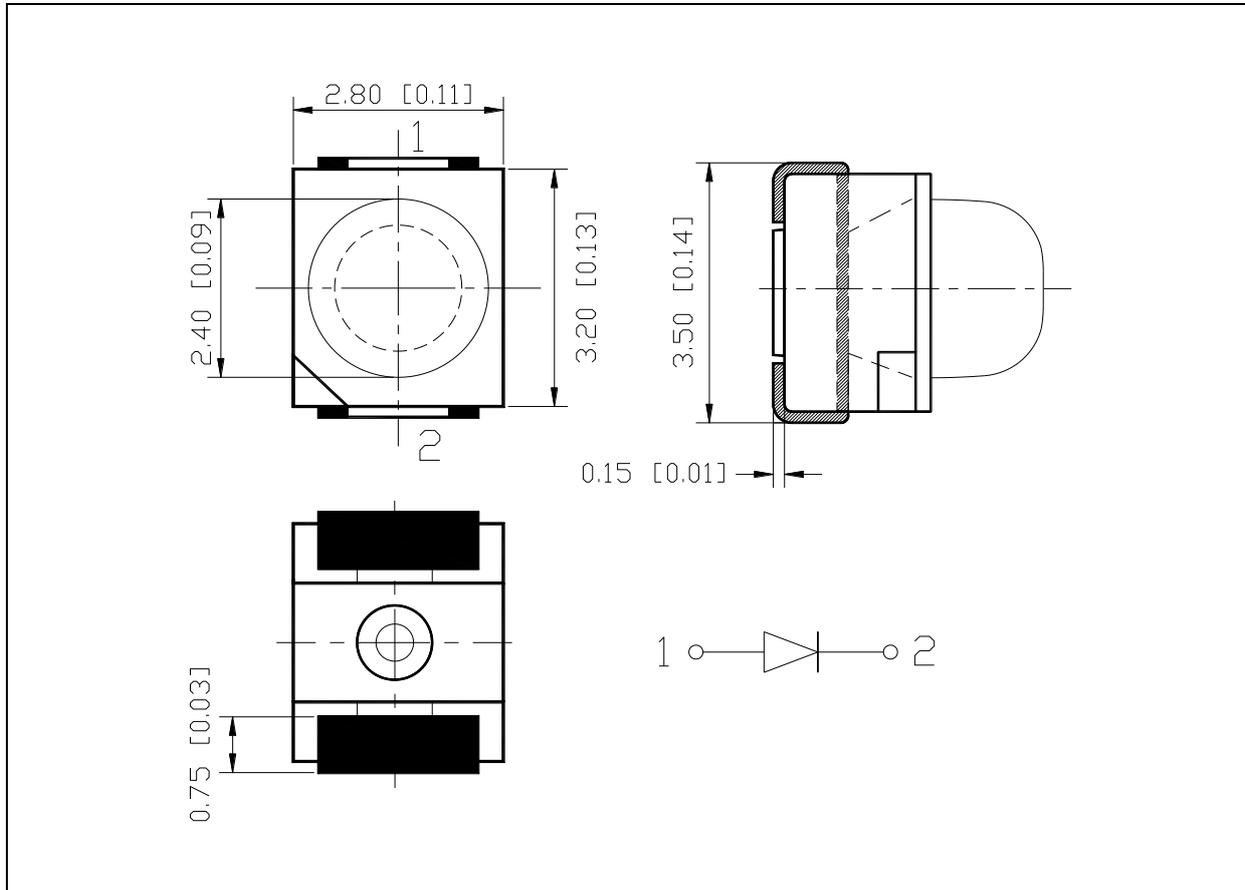
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	2.8	3.2	3.7	V	I _F =20mA
Luminous Intensity	I _v	4000	5900	11200	mcd	I _F =20mA
Dominant Wavelength	λ _D	495	500	505	nm	I _F =20mA
Peak Wavelength	λ _P	---	496	---	nm	I _F =20mA
Spectral Half Bandwidth	Δλ	---	26	---	nm	I _F =20mA
Viewing Angle	2θ _{1/2}	---	30	---	deg	I _F =20mA

1. Luminous intensity (I_v) ±15%, Forward Voltage (V_F) ±0.1V, Viewing angle(2θ_{1/2}) ±5%

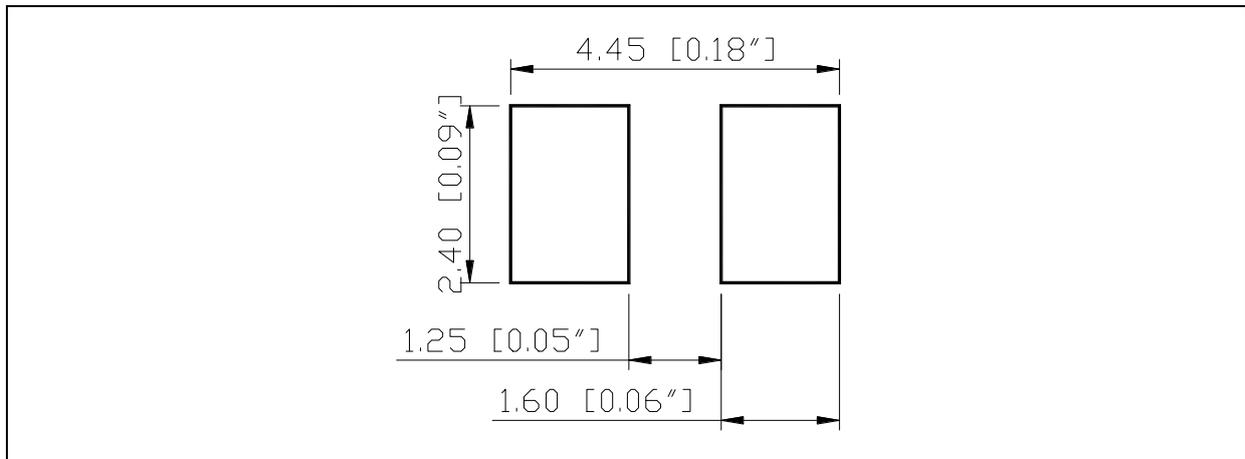
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.2 mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^\circ$.

BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
f	2.8	3.1	V
g	3.1	3.4	
h	3.4	3.7	

 Luminous Intensity Classifications ($I_F = 20\text{mA}$):

Code	Min.	Max.	Unit
Z	4000	5200	mcd
a	5200	6800	
b	6800	8800	
c	8800	11200	

 Wavelength Classifications ($I_F = 20\text{mA}$):

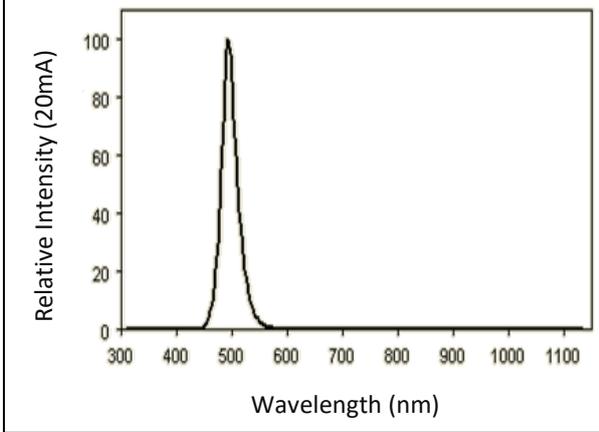
Code	Min.	Max.	Unit
g	495	497.5	nm
h	497.5	500	
M	500	502.5	
N	502.5	505	

Example Binning Information on Label:

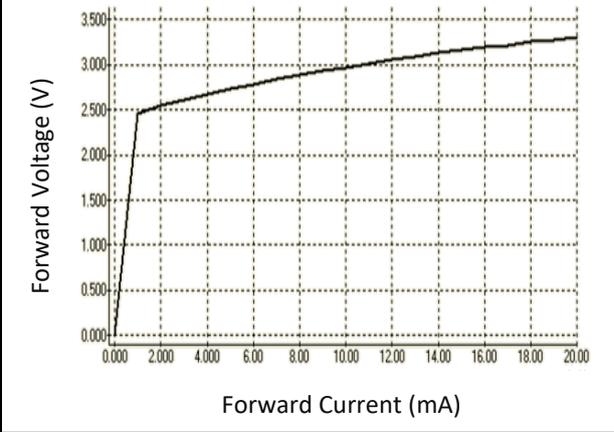
Code	Vf (V)	Iv (mcd)	λ_d (nm)	Test Condition
gah 20	g= 3.1~3.4	a= 5200~6800	h= 497.5~500	20= 20mA

ELECTRO-OPTICAL CHARACTERISTICS:

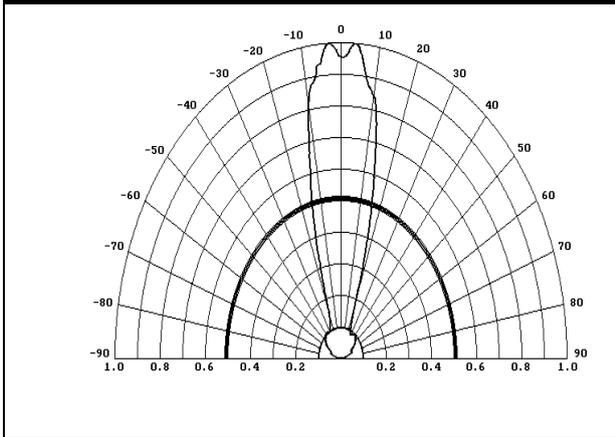
Relative Spectral Distribution



Forward Current v.s. Forward Voltage

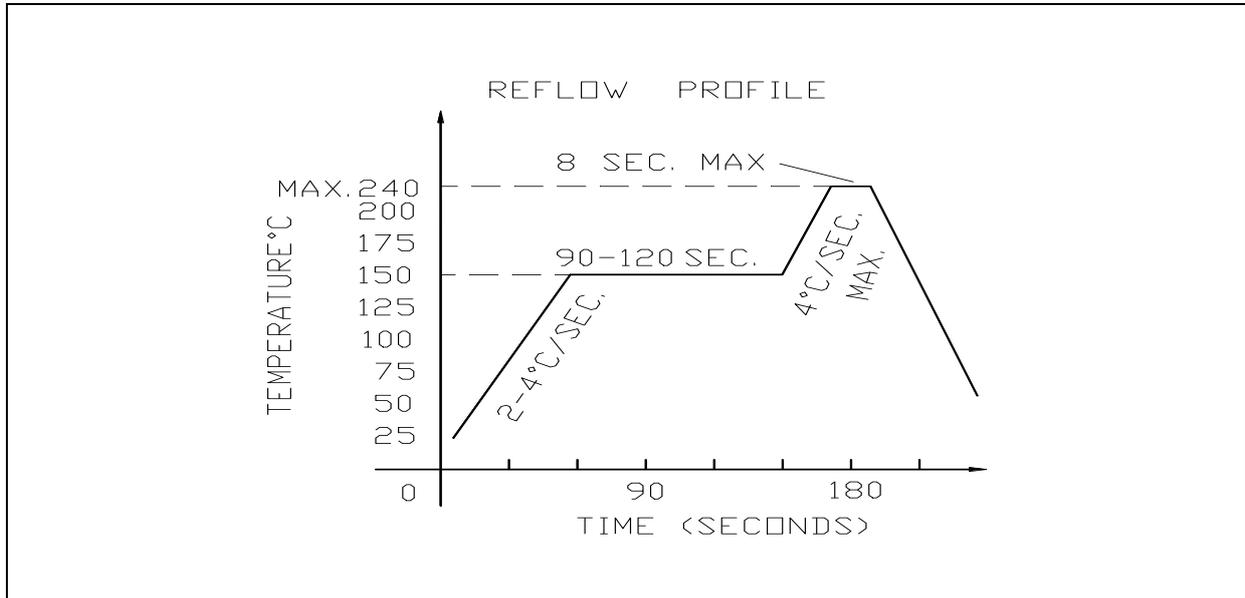


Directive Radiation



RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:

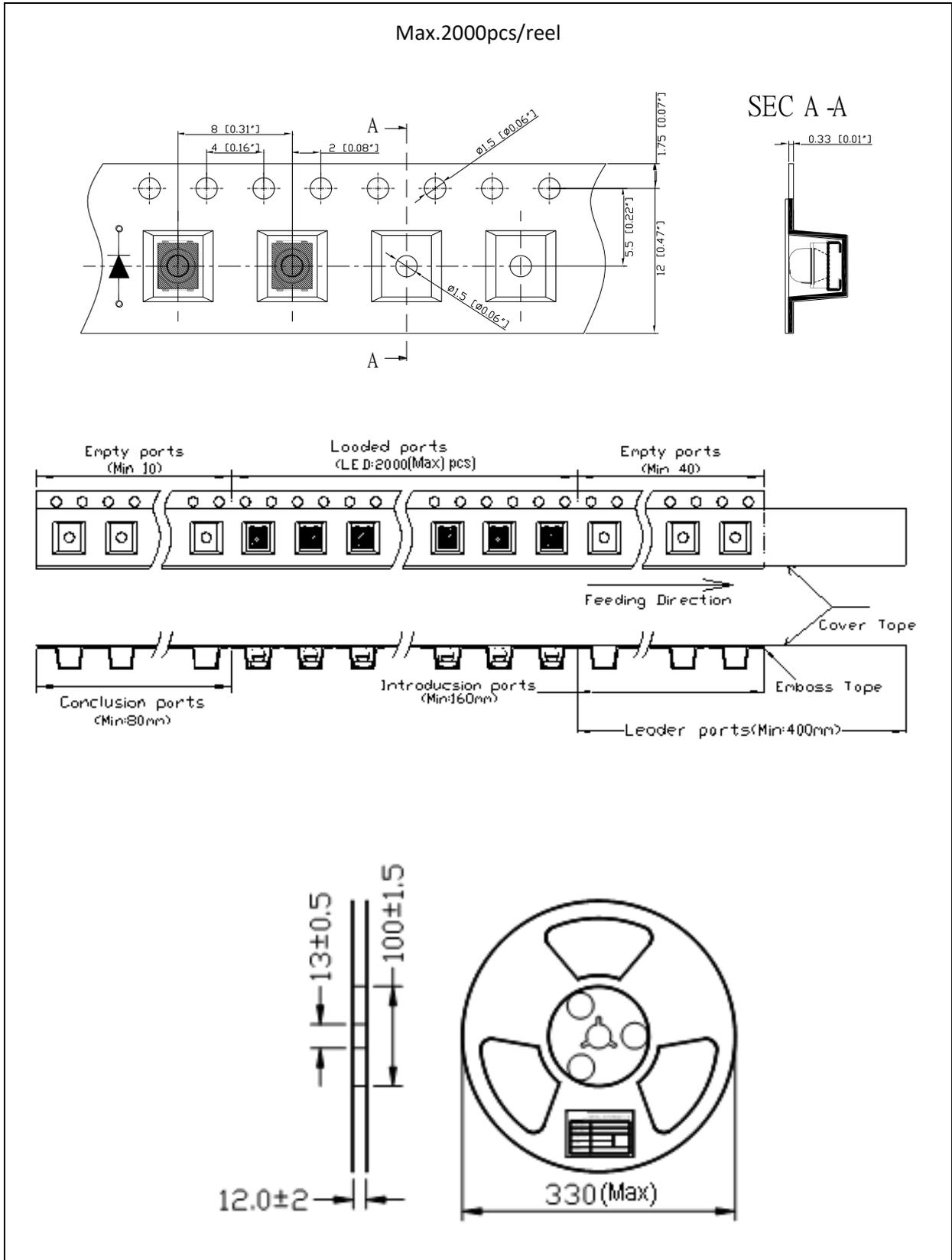


Note:

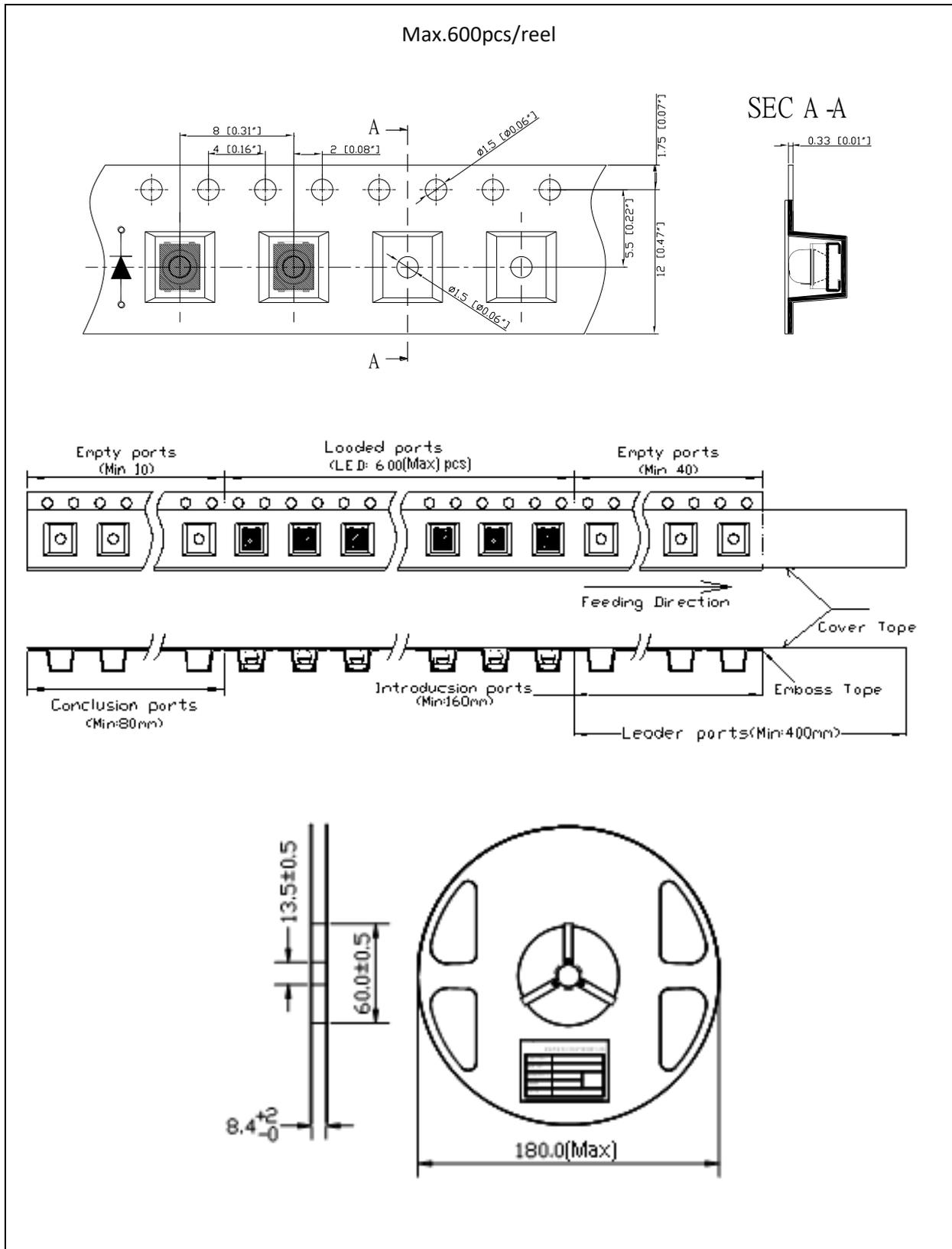
1. Maximum reflow soldering: 1 time.
2. The maximum soldering temperature is 240°C. The maximum soldering temperature should be limited to 260°C.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

NOB53S01 - 13" Reel Dimension:



N0B53S01SR - 7" Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking before use.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	29/09/2020	Datasheet set-up.
A1.1	21/05/2024	Revise part number description.
A1.2	18/07/2024	Add 7'' reel packing information.